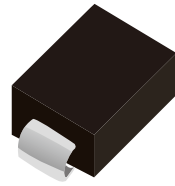


FEATURES

- Excellent capability of absorbing transient surge
- Quick response to surge voltage
- Eliminates over voltage caused by fast rising transients
- Solid-state silicon technology, non degenerate



SMB(DO-214AA)



Marking



Schematic Symbol

APPLICATIONS

- Audio/Video line
- Network and telecom
- Data lines and security systems
- Serial ports

APPROVALS

RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003

ELECTRICAL CHARACTERISTICS

Part Number	V_{DRM}	V_S	V_T	I_{DRM}	I_S	I_T	I_H	C_o
	Min. (V)	Max. (V)	Max. (V)	Max. (μA)	mA	Max. (A)	Min. (mA)	Typ.(pF)
P0080SB-MC	6.0	25.0	4.0	5.0	800.0	2.2	40.0	20.0

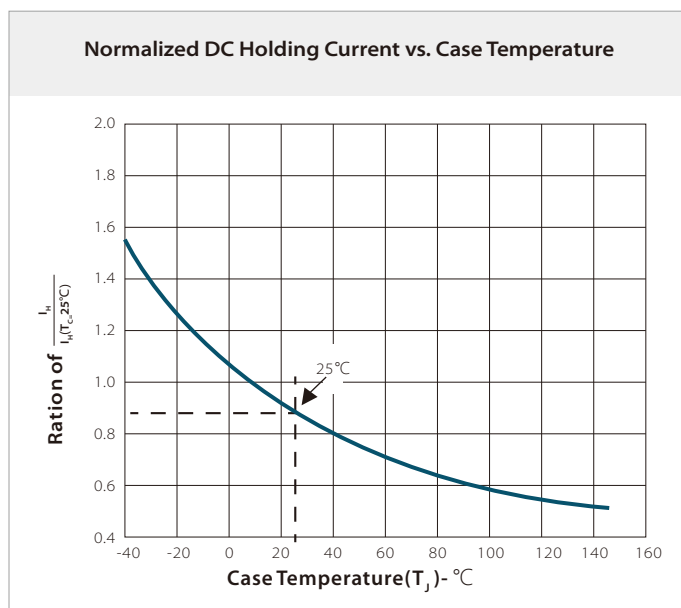
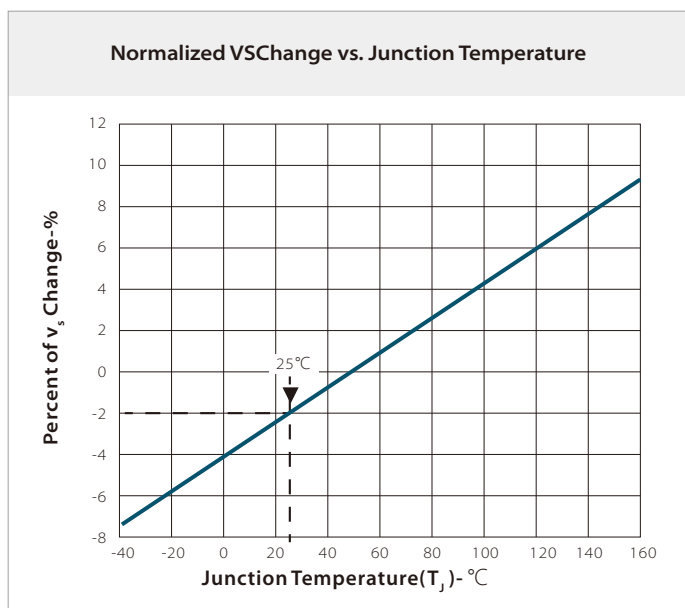
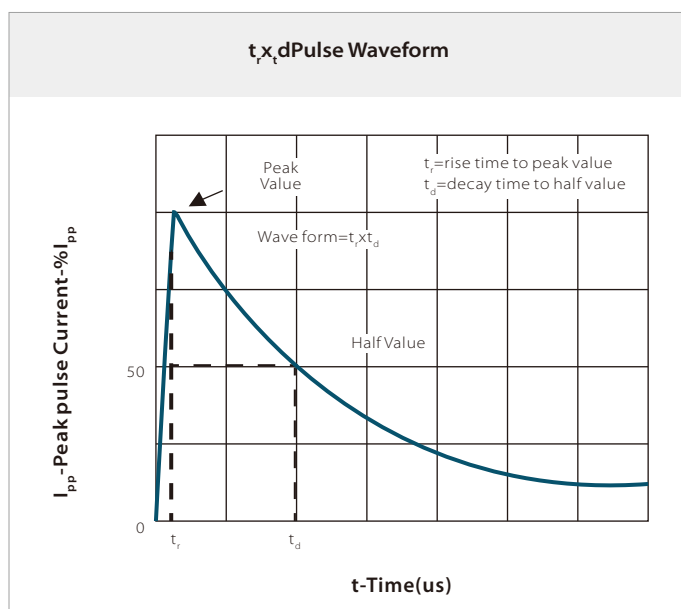
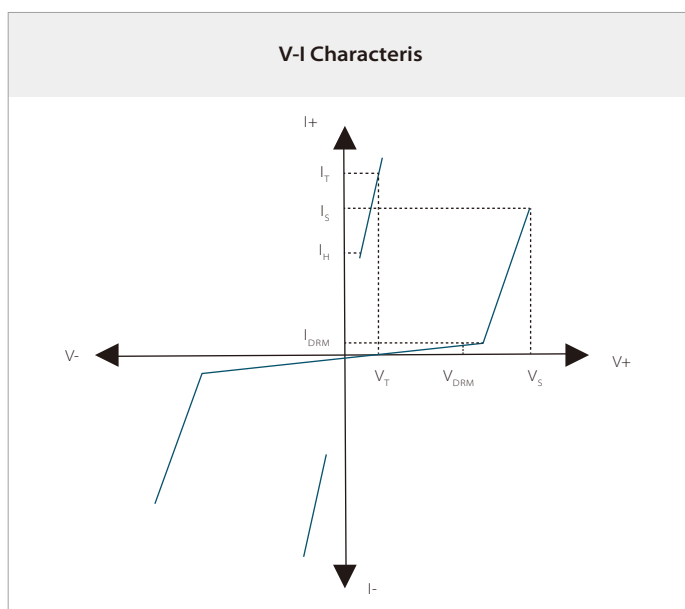
SURGE RATINGS

Part Number	I_{PP} 2x10 μs	I_{PP} 8x20 μs	I_{PP} 10x560 μs	I_{PP} 10x1000 μs	V_{PP} 10x700 μs	I_{TSM} 50/60Hz	d_i/d_t
	(A)	(A)	(A)	(A)	(V)	(A)	(A/ μs)
P0080SB-MC	250	250	100	80	4000	25	500

THERMAL CONSIDERATIONS

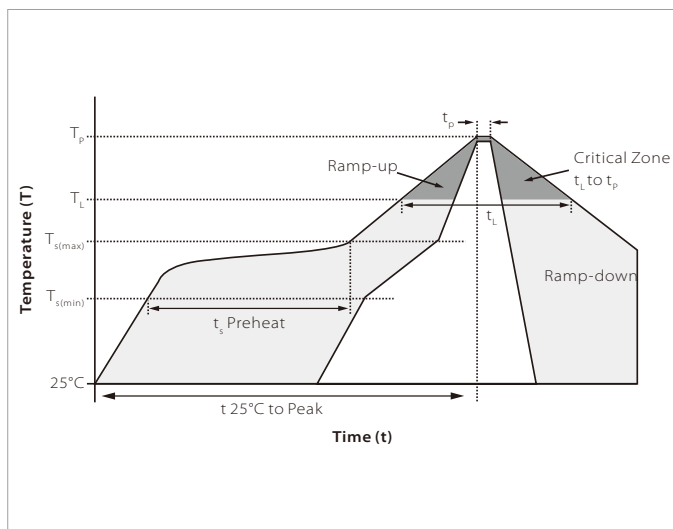
Symbol	Parameter	Value	Unit
$R_{\theta JA}$	Junction to Ambient on printed circuit	90	$^{\circ}\text{C}/\text{W}$
T_J	Operating Junction Temperature	-55 to +125	$^{\circ}\text{C}$
T_{STG}	Storage Temperature Range	-55 to +150	$^{\circ}\text{C}$

RATINGS AND CHARACTERISTIC CURVES ($T_A = 25^{\circ}\text{C}$)

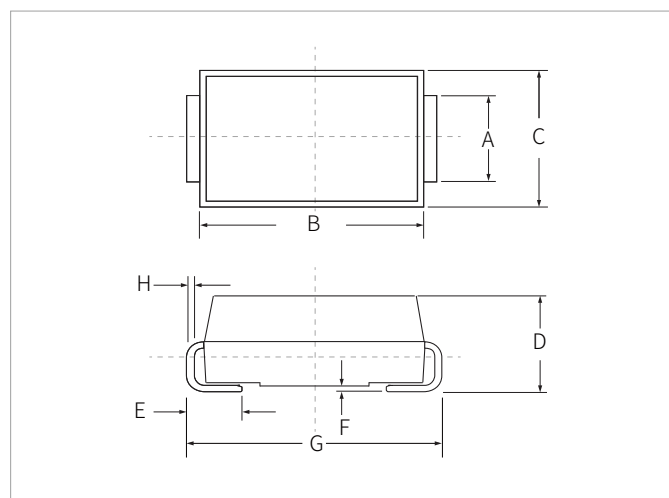


SOLDERING PARAMETERS

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Max ($T_{s(min)}$)	150°C
	Temperature Max ($T_{s(max)}$)	200°C
	Time (min to max) (t_p)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Time (min to max) (t_p)	60 – 150 seconds
Peak Temperature (T_p)		260°C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260°C

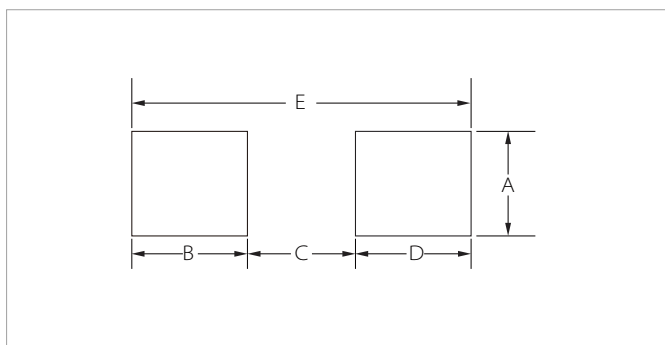


DO-214AA(SMB) PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min	Max	Min	Max
A	1.96	2.20	0.077	0.087
B	5.10	5.50	0.201	0.216
C	3.40	3.90	0.134	0.153
D	2.15	2.75	0.085	0.108
E	0.76	1.52	0.030	0.060
F	0.02	0.20	0.001	0.008
G	5.08	5.59	0.200	0.220
H	0.15	0.30	0.006	0.012

RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.20	-	0.087	-
B	1.45	-	0.057	-
C	-	2.55	-	0.010
D	1.45	-	0.057	-
E	5.60REF		0.220REF	

ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
P0080SB-MC	DO-214AA(SMB)	3000PCS	13"

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